

Title (en)

Process and device for the placement of infiltration materials behind building elements

Title (de)

Verfahren und Vorrichtung zum Einbringen von Materialien hinter Bauteilen

Title (fr)

Procédé et dispositif pour le placement de matériaux d'infiltration derrière des éléments de construction

Publication

**EP 0980935 A3 20010321 (DE)**

Application

**EP 99116236 A 19990817**

Priority

DE 19837055 A 19980817

Abstract (en)

[origin: EP0980935A2] The injection device is introduced into the component part (1) and an injection jet of material is moved through the device to exit behind the component part where it is deflected by a deflection device which changes its direction of movement into a sealing position. An opening is first drilled in the component part and then lined in the inlet area by a tubular object such as a dowel to ensure close contact between opening and injection device.

IPC 1-7

**E04B 1/64**; **E04G 23/02**

IPC 8 full level

**E04B 1/64** (2006.01); **E04G 23/02** (2006.01)

CPC (source: EP)

**E04B 1/64** (2013.01)

Citation (search report)

- [XAY] US 4520051 A 19850528 - HARRISON GEORGE W [US]
- [X] EP 0725195 A2 19960807 - RASCOR SPEZIALBAU GMBH [DE]
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Designated contracting state (EPC)

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DOCDB simple family (publication)

**EP 0980935 A2 20000223**; **EP 0980935 A3 20010321**; **EP 0980935 B1 20041013**; AT E279599 T1 20041015; DE 19837055 A1 20000302; DE 19837055 C2 20030116; DE 59910808 D1 20041118

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